

2.5V PHASE LOCKED LOOP CLOCK DRIVER

IDTCSPT855

FFATURFS:

- PLL clock driver for DDR (Double Data Rate) synchronous DRAM applications
- · Spread spectrum clock compatible
- · Operating frequency: 60MHz to 220MHz
- · Low jitter (cycle-to-cycle): ±50ps
- Distributes one differential clock input to four differential clock outputs
- Enters low power mode and 3-state outputs when input CLK signal is less than 20MHz or PWRDWN is low
- · Operates from a 2.5V supply
- Consumes <200µA quiescent current
- External feedback pins (FBIN, FBIN) are used to synchronize outputs to input clocks
- · Available in TSSOP package

APPLICATIONS:

 For all DDR1 speeds: PC1600 (DDR200), PC2100 (DDR266), PC2700 (DDR333), PC3200 (DDR400)

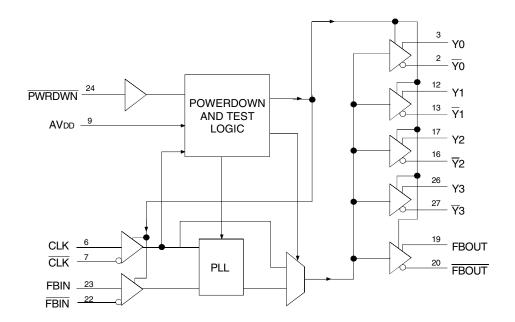
DESCRIPTION:

The CSPT855 is a high-performance, low-skew, low-jitter zero delay buffer that distributes one differential clock input pair (CLK, $\overline{\text{CLK}}$) to four differential output pairs (Y [0:3], $\overline{\text{Y}[0:3]}$) and one differential pair of feedback clock outputs (FBOUT, $\overline{\text{FBOUT}}$). When $\overline{\text{PWRDWN}}$ is high, the outputs switch in phase and frequency with CLK. When $\overline{\text{PWRDWN}}$ is low, all outputs are disabled to a high-impedance state (3-state), and the PLL is shut down (low-power mode). The device also enters this low-power mode when the input frequency falls below a suggested detection frequency that is below 20MHz (typical 10MHz). An input frequency detection circuit detects the low-frequency condition, and after applying a >20MHz input signal, this detection circuit reactivates the PLL and enables the outputs.

When AVDD is tied to GND, the PLL is turned off and bypassed for test purposes. The CSPT855 is also able to track spread spectrum clocking for reduced EMI.

Since the CSPT855 is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up.

FUNCTIONAL BLOCK DIAGRAM

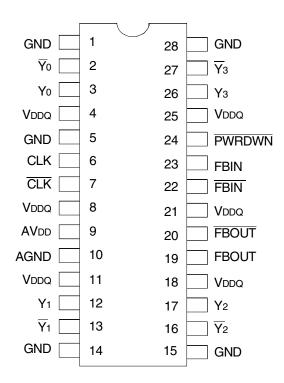


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COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

NOVEMBER 2008

PIN CONFIGURATION



TSSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Max	Unit
Vddq, AVdd	Supply Voltage Range	-0.5 to +3.6	V
VI ⁽²⁾	Input Voltage Range	-0.5 to VDDQ + 0.5	V
Vo ⁽²⁾	Output Voltage Range	-0.5 to VDDQ + 0.5	V
lik (Vi < 0 or	Input Clamp Current	±50	mA
VI < VDDQ)			
IOK (Vo < 0 or	Output Clamp Current	±50	mA
Vo > Vddq)			
lo	Continuous Output Current	±50	mA
(VO = 0 to VDDQ)			
VDDQ or GND	Continuous Current	±100	mA
θJA ⁽³⁾	Package Thermal Impedance	105.8	°C/W
Tstg	Storage Temperature Range	– 65 to +150	°C

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
 permanent damage to the device. This is a stress rating only and functional operation
 of the device at these or any other conditions above those indicated in the operational
 sections of this specification is not implied. Exposure to absolute maximum rating
 conditions for extended periods may affect reliability.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. This value is limited to 3.6V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

PIN DESCRIPTION

Pin Name	Pin Number	I/O	Description
AGND	10		Ground for analog supply
AVDD	9		Analog supply
CLK, CLK	6, 7	- 1	Differential clock input
FBIN, FBIN	22,23	I	Feedback differential clock input
FBOUT, FBOUT	19,20	0	Feedback differential clock output
GND	1, 5, 14, 15, 28		Ground
PWRDWN	24	I	Control input to turn device in the power-down mode
VDDQ	4, 8, 11, 18, 21, 25		I/O supply
Y[0:3]	3, 12, 17, 26	0	Buffered output copies of input clock, CLK
Y[0:3]	2, 13, 16, 27	0	Buffered output copies of input clock, CLK

FUNCTION TABLE(1)

INPUTS					OUTPUTS			
AVDD	PWRDWN	CLK	CLK	Υ	Ÿ	FBOUT	FBOUT	PLL
GND	Н	L	Н	L	Н	L	Н	Bypassed/OFF
GND	Н	Н	L	Н	L	Н	L	Bypassed/OFF
Х	L	L	Н	Z	Z	Z	Z	OFF
Х	L	Н	L	Z	Z	Z	Z	OFF
2.5V (nom)	Н	L	Н	L	Н	L	Н	ON
2.5V (nom)	Н	Н	L	Н	L	Н	L	ON
2.5V (nom)	Х	<20MHz ⁽²⁾	<20MHz ⁽²⁾	Z	Z	Z	Z	OFF

NOTES:

- 1. H = HIGH Voltage Level
 - L = LOW Voltage Level
 - Z = High-Impedance OFF-State
 - X = Don't Care
- 2. Typically 10MHz.

RECOMMENDED OPERATING CONDITIONS(1)

Symbol	Paramet	Min.	Тур.	Max.	Unit	
AVDD, VDDQ	Supply Voltage		2.3	_	2.7	V
VIL	Input Voltage LOW	CLK, CLK, FBIN, FBIN	_	_	VDDQ/2-0.18	V
		PRWDWN	- 0.3	_	0.7	
VIH	Input Voltage HIGH CLK, CLK, FBIN, FBIN		VDDQ/2 + 0.18	_	_	V
		PRWDWN	1.7	_	VDDQ + 0.3	
	DC Input Signal Voltage ⁽²⁾		- 0.3	_	VDDQ	V
VID	Differential Input Signal Voltage ⁽³⁾ CLK, FBIN		0.36	_	VDDQ + 0.6	V
Vo(x)	Output Differential Cross-Voltage ⁽⁴⁾	VDDQ/2 - 0.2	VDDQ/2	VDDQ/2 + 0.2	V	
VI(X)	Input Differential Pair Cross-Voltage(4)	Input Differential Pair Cross-Voltage ⁽⁴⁾			VDDQ/2 + 0.2	V
Іон	HIGH-Level Output Current		_	_	- 12	mA
loL	LOW-Level Output Current		_	_	12	mA
SR	Input Slew Rate, see figure 8		1	_	4	V/ns
TA	Operating Free-Air Temperature Commercial		0		+70	°C
		Industrial	-40	_	+85	

NOTES:

- 1. Unused inputs must be held HIGH or LOW to prevent them from floating.
- 2. DC input signal voltage specifies the allowable DC execution of differential input.
- 3. Differential input signal voltage specifies the differential voltage | VTR VCP | required for switching, where VTR is the true input level and VcP is the complementary input level.
- 4. Differential cross-point voltage is expected to track variations of VDDQ and is the voltage at which the differential signals must be crossing.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial: $TA = 0^{\circ}C$ to $+70^{\circ}C$; Industrial: $TA = -40^{\circ}C$ to $+85^{\circ}C$

Symbol	Parameter	Parameter Conditions		Min.	Тур.(1)	Max.	Unit
Vik	Input Voltage (All Inputs)		VDDQ = 2.3V, II = -18mA	_	_	-1.2	V
Vон	HIGH-Level Output Voltage	;	VDDQ = Min. to Max., IOH = -1mA	VDDQ - 0.1	_	_	V
			VDDQ = 2.3V, IOH = -12mA	1.7	_	_	
Vol	LOW-Level Output Voltage		VDDQ = Min. to Max., IOL = 1mA	_	_	0.1	V
			VDDQ = 2.3V, IOL = 12mA	_	_	0.6	İ
Іон	HIGH-Level Output Curren	t	VDDQ = 2.3V, VO = 1V	-18	-32	_	mA
lol	LOW-Level Output Current		VDDQ = 2.3V, Vo = 1.2V	26	35	_	mA
Vod	Output Voltage Swing		Differential outputs are terminated with 120Ω	1.1	_	VDDQ-0.4	V
Vox	Output Differential Cross Voltage ⁽²⁾		Differential outputs are terminated with 120Ω	VDDQ/2-0.2	VDDQ/2	VDDQ/2 + 0.2	V
lı	Input Current		VDDQ = 2.7V, VI = 0V to 2.7V	_	_	±10	μΑ
loz	High-Impedance State Output Current		VDDQ = 2.7V, VO = VDDQ or GND	_	_	±10	μΑ
IDD(PD)	Power-Down Current on Vo	DDQ and AVDD	CLK and CLK = 0MHz, PWRDWN = LOW,	_	100	200	μΑ
			Σ of IDD and AIDD				İ
IDD	Dynamic Current on VDDQ	CL = 14pF	$fo = 167MHz$, Differential outputs terminated with 120Ω	_	150	180	mA
	C _L = 0pF		$fo = 167MHz$, Differential outputs terminated with 120Ω	_	130	160	İ
Aldd	Supply Current on AVDD		fo = 167MHz	_	8	10	mA
Сі	Input Capacitance		VDDQ = 2.5V, VI = VDDQ or GND	2	2.5	3	pF
Со	Output Capacitance		VDDQ = 2.5V, VI = VDDQ or GND	2.5	3	3.5	pF

NOTES:

- 1. All typical values are at respective nominal VDDQ.
- 2. Differential cross-point voltage is expected to track variation of VDDQ and is the voltage at which the differential signals must be crossing.

TIMING REQUIREMENTS

Symbol	Parameter	Min.	Max.	Unit
fclk	Operating Clock Frequency	60	220	MHz
toc	Input Clock Duty Cycle	40	60	%
t_	Stabilization Time (PLL Mode) ⁽¹⁾	_	10	μs
tL.	Stabilization Time (Bypass Mode) ⁽²⁾	_	30	ns

NOTES:

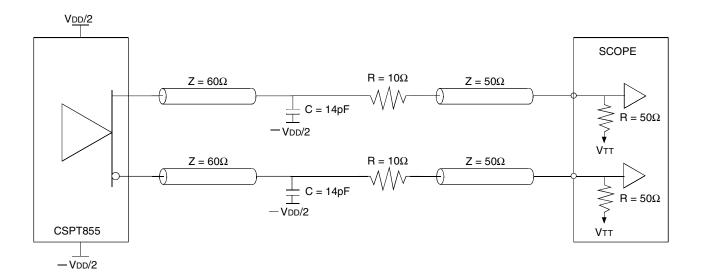
- 1. Recovery time required when the device goes from power-down mode into bypass mode (test mode with AVDD at GND).
- 2. Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

SWITCHING CHARACTERISTICS

Symbol	Description		Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
t _{PLH} (2)	LOW to HIGH Level Propagation Delay Time		Test mode, CLK to any output	_	4.5	_	ns
t _{PHL} (2)	HIGH to LOW Level Propagation Delay Time		Test mode, CLK to any output	_	4.5	_	ns
UIT(PER) ⁽³⁾	Jitter (period), see figure 6		66MHz	- 55	_	55	ps
			100/ 133/ 167/ 200 MHz	-35	_	35	
t/IT(CC) ⁽³⁾	Jitter (cycle-to-cycle), see figure 2		66MHz	- 60	_	60	ps
			100/ 133/ 167/ 200 MHz	-50	_	50]
UIT(HPER)(3)	Half-Period Jitter, see figure 7		66MHz	-130	_	130	
			100MHz	- 90	_	90	ps
			133/ 167/ 200 MHz	- 75	_	75]
tslr(0)	SLR(O) Output Clock Slew Rate (single-ended), see figure 8		Load: 120Ω / 14pF	1	_	2	V/ns
			Load: 120Ω / 4pF	1	_	3]
			66MHz	-180 —	_	180	
		SSC Off	100/ 133 MHz	-130	_	130	
tD(∅) ⁽³⁾	Dynamic Phase Offset (includes jitter)		167/ 200 MHz	- 90	_	90	ps
	see figure 4		66MHz	-230	_	230	
		SSC On	100/ 133 MHz	-170	_	170]
		167/	167/ 200 MHz	-100	_	100]
t(∅)	Static Phase Offset, see figure 3		66MHz	-150	_	150	
			100/ 133/ 167 MHz	-100	_	100	ps
			200MHz	- 50	_	50	1
tsk(o) ⁽⁴⁾	Output Skew, see figure 5			_	_	50	ps
tr,tf	Output Rise and Fall Times (20% to 80%)		Load: 120Ω / 14pF	650	_	900	ps

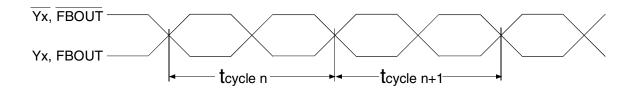
NOTES:

- 1. All typical values are at respective nominal VDDQ.
- 2. Refers to transition of non-inverting output.
- 3. This parameter guaranteed by design but not production tested.
- 4. All differential output pins are terminated with 120 Ω / 14pF.



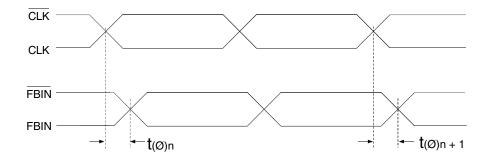
NOTE:1. V(TT) = GND

Figure 1. Output Load Test Circuit



 $t_{jit(cc)} = t_{cycle n} - t_{cycle n+1}$

Figure 2. Cycle-to-Cycle jitter



$$t_{(\emptyset)} = \frac{\sum_{1}^{n=N} t_{(\emptyset)n}}{N}$$

(N is a large number of samples)

Figure 3. Static Phase Offset

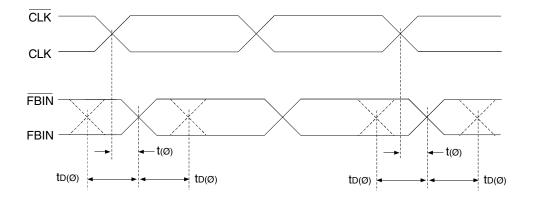


Figure 4. Dynamic Phase Offset

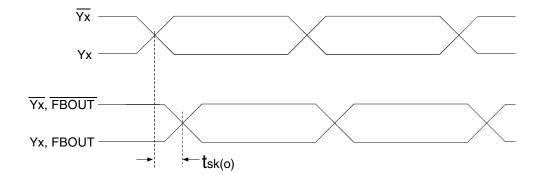
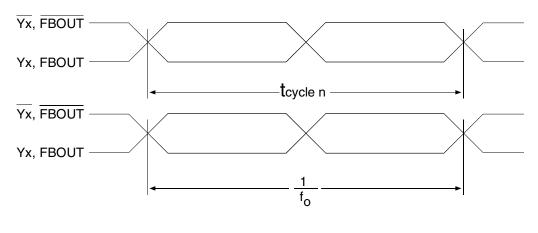


Figure 5. Output Skew



$$t_{jit(per)} = t_{cycle n} - \frac{1}{f_o}$$

Figure 6. Period jitter

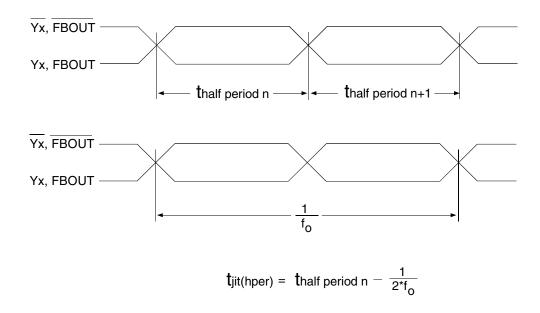


Figure 7. Half-Period jitter



Figure 8. Input and Output Slew Rates

ORDERING INFORMATION

